

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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60V Nch+Nch Power MOSFET

V _{DSS}	60V
R _{DS(on)} (Max.)	65mΩ
I _D	±4.5A
P_{D}	2.0W

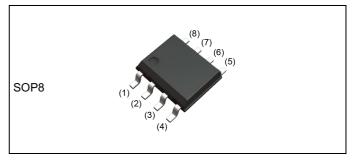
Features

- 1) Low on resistance
- 2) Small Surface Mount Package (SOP8)
- 3) Pb-free lead plating; RoHS compliant
- 4) AEC-Q101 Qualified

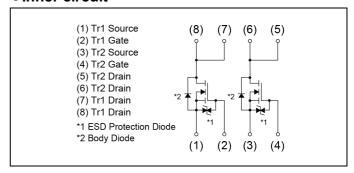
Application

Switching

Outline



•Inner circuit



Packaging specifications

	Packing	Embossed Tape
Type	Reel size (mm)	330
	Tape width (mm)	12
	Basic ordering unit (pcs)	2500
	Taping code	ТВ
	Marking	SP8K32

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified) < Tr1 and Tr2>

Parameter	Symbol	Value	Unit	
Drain - Source voltage	V _{DSS}	60	V	
Continuous drain current	I _D	±4.5	Α	
Pulsed drain current	I _{DP} *1	±18	Α	
Gate - Source voltage	V _{GSS}	±20	V	
Device discipation (Astal)	P _D *2	2.0	W	
Power dissipation (total)	P _D *3	1.4		
Junction temperature	T _j	150	°C	
Operating junction and storage temperature range	T _{stg}	-55 to +150	°C	

●Thermal resistance

Downston	Currele el	Values			I India
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal registeres in action, ambient (total)	R _{thJA} *2	-	-	62.5	°C/W
Thermal resistance, junction - ambient (total)	R _{thJA} *3	-	-	89.2	C/VV

● Electrical characteristics (T_a = 25°C) < Tr1 and Tr2>

Davanatas	Current el	Conditions	Values			Unit	
Parameter	Symbol	mbol Conditions -		Тур.	Max.	Offic	
Drain - Source breakdown voltage	V _{(BR)DSS}	$V_{GS} = 0V$, $I_D = 1mA$	60	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	I _D = 1mA referenced to 25°C	-	63.7	-	mV/°C	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 60V, V _{GS} = 0V	-	-	1	μА	
Gate - Source leakage current	I _{GSS}	V _{DS} = 0V, V _{GS} = ±20V	-	-	±10	μА	
Gate threshold voltage	V _{GS(th)}	V _{DS} = 10V, I _D = 1mA	1.0	-	2.5	V	
Gate threshold voltage temperature coefficient	$\frac{\DeltaV_{GS(th)}}{\DeltaT_j}$			-2.8	-	mV/°C	
		V _{GS} = 10V, I _D = 4.5A	-	46	65		
Static drain - source on - state resistance	R _{DS(on)} *4	V _{GS} = 4.5V, I _D = 4.5A	-	52	73	mΩ	
on state resistance		V _{GS} = 4.0V, I _D = 4.5A	-	55	77		
Gate resistance	R_{G}	f = 1MHz, open drain	-	5.9	-	Ω	
Forward Transfer Admittance	Y _{fs} *4	V _{DS} = 10V, I _D = 4.5A	4.0	-	-	S	

^{*1} Pw \leq 10 μ s, Duty cycle \leq 1%

^{*2} Mounted on a ceramic board (30×30×0.8mm)

^{*3} Mounted on a FR4 (25×25×0.8mm)

^{*4} Pulsed

●Electrical characteristics (T_a = 25°C) <Tr1 and Tr2>

Parameter	Cymahal	Conditions	Values			Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offic	
Input capacitance	C _{iss}	V _{GS} = 0V	-	500	-		
Output capacitance	C _{oss}	V _{DS} = 10V	-	120	-	pF	
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	55	-		
Turn - on delay time	t _{d(on)} *4	V _{DD} ≈ 30V,V _{GS} = 10V	-	12	-		
Rise time	t _r *4	I _D = 2.3A	-	18	-		
Turn - off delay time	t _{d(off)} *4	$R_L = 13\Omega$	-	40	-	ns	
Fall time	t _f *4	$R_G = 10\Omega$	-	13	-		

ullet Gate charge characteristics (T_a = 25°C) <Tr1 and Tr2>

Parameter	Symbol	Conditions	Values			Unit
raianetei	Symbol	Conditions	Min.	Тур.	Max.	Offic
Total gate charge	Q_g^{*4}		-	7.0	10	
Gate - Source charge	Q _{gs} *4	$V_{DD} \approx 30V$, $I_D = 4.5A$ $V_{GS} = 5V$	-	1.6	-	nC
Gate - Drain charge	Q _{gd} *4	1.00	-	2.5	-	

●Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

<Tr1 and Tr2>

Parameter	Cymbol	Conditions	Values			Unit	
raianetei	Symbol	Conditions	Min.	Тур.	Max.	Offic	
Continuous forward current	I _S	T - 25°C	-	-	1.0	Δ.	
Pulse forward current	I _{SP} *1	T _a = 25°C	-	-	18	Α	
Forward voltage	V _{SD} *4	V _{GS} = 0V, I _S = 4.5A	-	-	1.2	V	

Fig.1 Power Dissipation Derating Curve

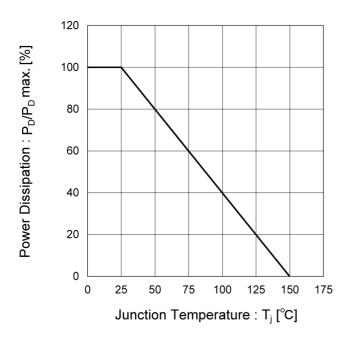
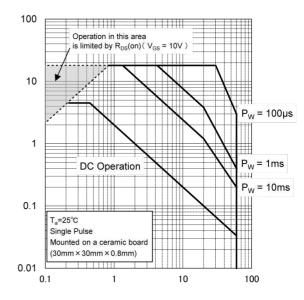


Fig.2 Maximum Safe Operating Area



Drain Current : I_D [A]

Drain - Source Voltage: V_{DS}[V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

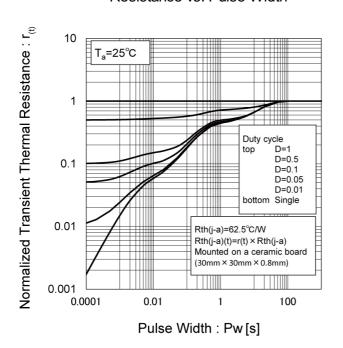


Fig.4 Single Pulse Maximum Power dissipation

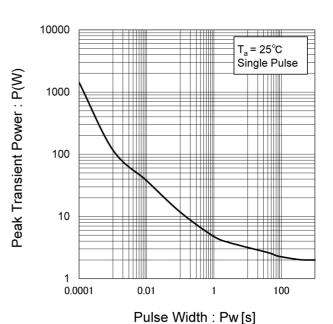


Fig.5 Typical Output Characteristics(I)

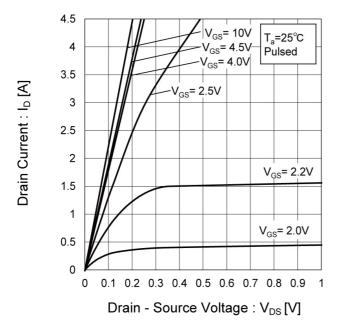
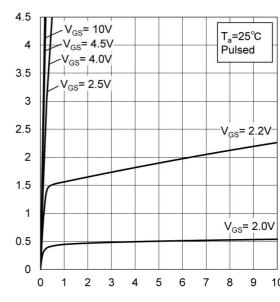


Fig.6 Typical Output Characteristics(II)



Drain Current : I_D [A]

Drain - Source Voltage : V_{DS} [V]

Fig.7 Breakdown Voltage vs.
Junction Temperature

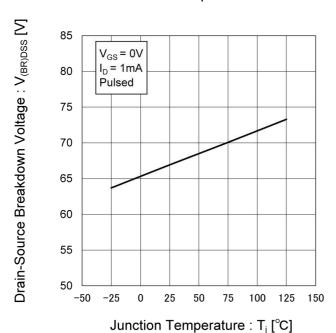


Fig.8 Typical Transfer Characteristics

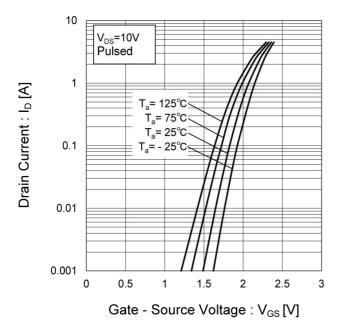


Fig.9 Gate Threshold Voltage vs.
Junction Temperature

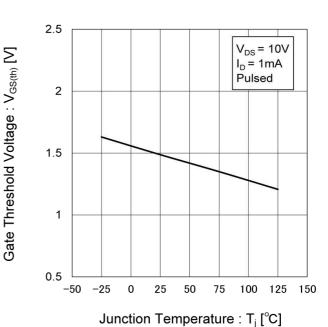


Fig.10 Forward Transfer Admittance vs.
Drain Current

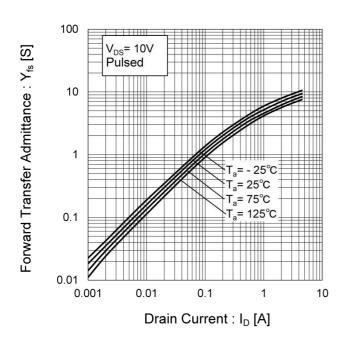


Fig.11 Drain Current Derating Curve

120 100 **Drain Current Dissipation** 80 : I_D/I_Dmax. [%] 60 40 20 0 -25 0 25 50 75 100 125 150 Junction Temperature : T_j [°C]

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

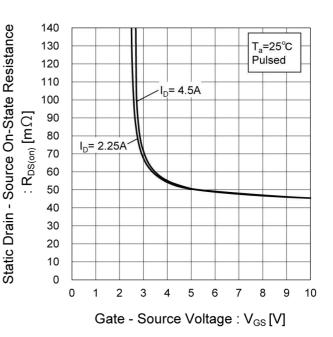


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

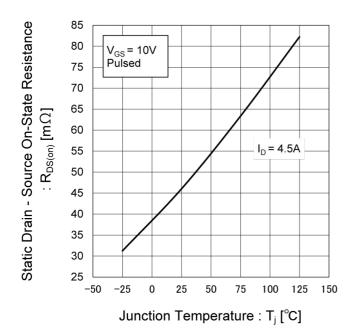


Fig.14 Static Drain - Source On - State
Resistance vs. Drain Current (I)

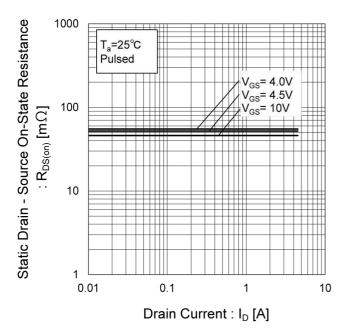


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

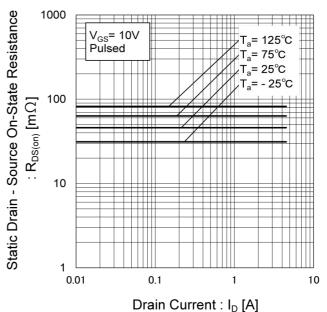


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)

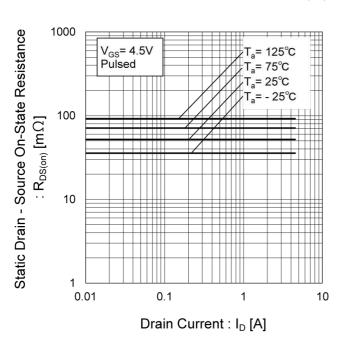


Fig.17 Static Drain - Source On - State Resistance vs. Drain Current (IV)

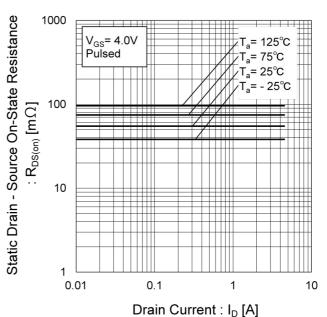


Fig.18 Typical Capacitance vs.

Drain - Source Voltage

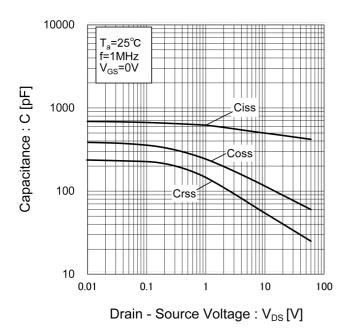


Fig.19 Switching Characteristics

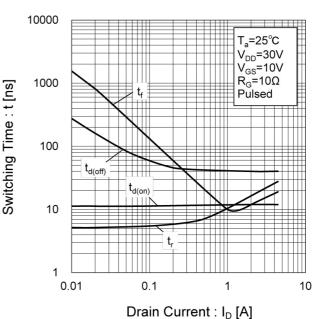


Fig.20 Dynamic Input Characteristics

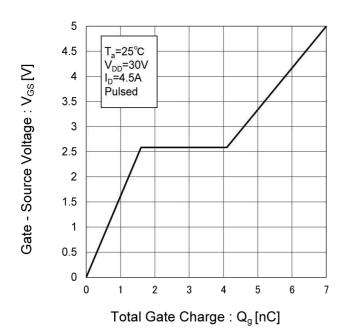
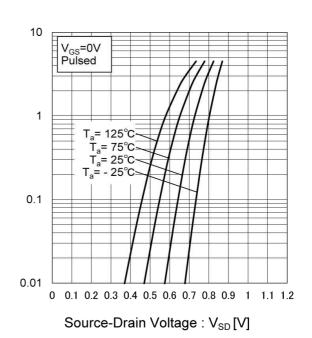


Fig.21 Source Current vs.

Source Drain Voltage



Source Current : Is [A]

• Measurement circuits < It is the same for the Tr1 and Tr2>

Fig.1-1 Switching Time Measurement Circuit

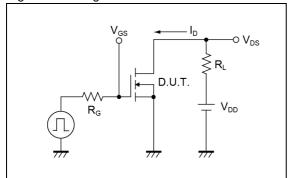


Fig.2-1 Gate Charge Measurement Circuit

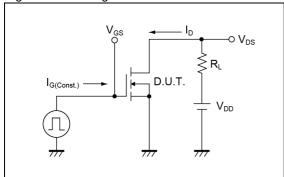


Fig.1-2 Switching Waveforms

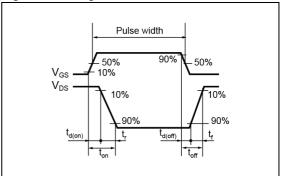
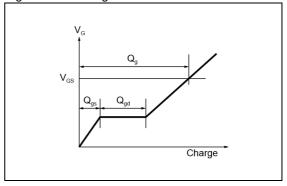
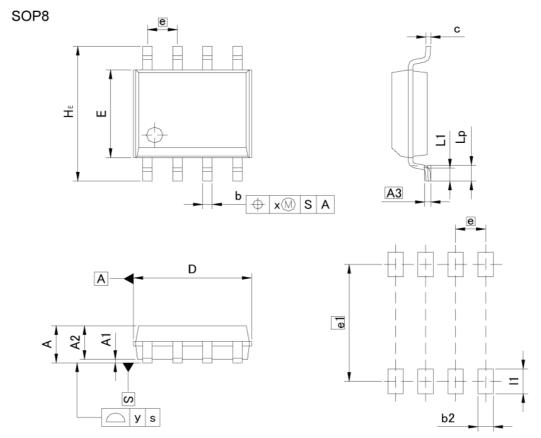


Fig.2-2 Gate Charge Waveform



Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	28	1.75	8	0.069	
A1	0.	15	0.0	06	
A2	1.40	1.60	0.055	0.063	
A3	0,	25	0.0	10	
b	0.30	0.50	0.012	0.020	
С	0.10	0.30	0.004	0.012	
D	4.80	5.20	0.189	0.205	
E	3.75	4.05	0.148	0.159	
е	1.	27	0.050		
HE	5.70	6.30	0.224	0.248	
L1	0.40	0.60	0.016	0.024	
Lp	0.65	0.85	0.026	0.033	
x	0.	15	0.0	.006	
У	0.10		0.0	04	
a MILI		ETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
b2		0.65		0.026	

Dimension in mm/inches

e1



0.045

0.203

1.15

5.15

Notice

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1. If you intend to use our Products in devices requiring extremely high reliability (such as medical equipment (Note 1), aircraft/spacecraft, nuclear power controllers, etc.) and whose malfunction or failure may cause loss of human life, bodily injury or serious damage to property ("Specific Applications"), please consult with the ROHM sales representative in advance. Unless otherwise agreed in writing by ROHM in advance, ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of any ROHM's Products for Specific Applications.

(Note1) Medical Equipment Classification of the Specific Applications

(1.1010 1) modical Equipment orderent and the operation upproduced							
JAPAN	USA	EU	CHINA				
CLASSIII	CLASSⅢ	CLASSIIb	CL ACCTI				
CLASSIV	CLASSIII	CLASSⅢ	CLASSⅢ				

- 2. ROHM designs and manufactures its Products subject to strict quality control system. However, semiconductor products can fail or malfunction at a certain rate. Please be sure to implement, at your own responsibilities, adequate safety measures including but not limited to fail-safe design against the physical injury, damage to any property, which a failure or malfunction of our Products may cause. The following are examples of safety measures:
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 - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
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 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

Precautions Regarding Application Examples and External Circuits

- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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